# SiA928DJ

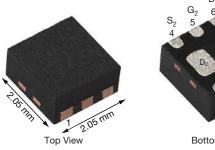


Vishay Siliconix

## Dual N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) MAX.	I <sub>D</sub> (A)	Q <sub>g</sub> (TYP.)		
30	0.025 at V <sub>GS</sub> = 10 V	4.5 <sup>a</sup>			
	0.029 at V <sub>GS</sub> = 6 V	4.5 <sup>a</sup>	3 nC		
	0.033 at V <sub>GS</sub> = 4.5 V	4.5 <sup>a</sup>			

#### PowerPAK<sup>®</sup> SC-70-6L Dual D





Marking Code: CM

### **Ordering Information:**

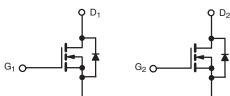
SiA928DJ-T1-GE3 (lead (Pb)-free and halogen free)

#### **FEATURES**

- TrenchFET<sup>®</sup> Gen IV power MOSFET
- Thermally enhanced PowerPAK<sup>®</sup> SC-70 package - Small footprint area - Low on-resistance
- 100 % R<sub>a</sub> tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **APPLICATIONS**

- · Portable devices such as smart phones, tablet PCs and mobile computing
- Load switch
- DC/DC converter
- Power management



N-Channel MOSFET 0 S1 N-Channel MOSFET O S<sub>2</sub>

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ , unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
Gate-Source Voltage		V <sub>GS</sub>	+20 / -16	v	
	T <sub>C</sub> = 25 °C		4.5 <sup>a</sup>		
	T <sub>C</sub> = 70 °C	- I <sub>D</sub> -	4.5 <sup>a</sup>		
Continuous Drain Current ( $T_J = 150 \ ^{\circ}C$ )	T <sub>A</sub> = 25 °C		4.5 <sup>a, b, c</sup>		
	T <sub>A</sub> = 70 °C		4.5 <sup>a, b, c</sup>	А	
Pulsed Drain Current (t = 100 µs)		I <sub>DM</sub>	30		
	T <sub>C</sub> = 25 °C		4.5 <sup>a</sup>		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub>	1.6 <sup>b, c</sup>		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		7.8		
	T <sub>C</sub> = 70 °C	P <sub>D</sub>	5		
	T <sub>A</sub> = 25 °C		1.9 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C	1	1.2 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	*0	
Soldering Recommendations (Peak temperature) d,e			260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient <sup>b, f</sup>	t ≤ 5 s	R <sub>thJA</sub>	52	65	°C/W	
Maximum Junction-to-Case (Drain)	Steady state	R <sub>thJC</sub>	12.5	16	0/10	

Notes

a. Package limited, T<sub>C</sub> = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

t = 5 s. c.

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state condition is 110 °C/W.

S16-1372-Rev. A, 11-Jul-16

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RoHS COMPLIANT HALOGEN FREE

SiA928DJ

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	I I			L		L	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \ \mu\text{A}$	30	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 A	-	14.7	-	mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-4.6	-		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1.2	-	2.2	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = +20 / -16 V$	-	-	± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}=30~V,~V_{GS}=0~V$	-	-	1	μA	
		$V_{DS}$ = 30 V, $V_{GS}$ = 0 V, $T_J$ = 55 $^\circ C$	-	-	10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \geq 5 \text{ V},  V_{GS} = 4.5 \text{ V}$	5	-	-	А	
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS}$ = 10 V, $I_D$ = 5 A	-	0.020	0.025	1	
	R <sub>DS(on)</sub>	$V_{GS} = 6 V$ , $I_D = 4 A$	-	0.023	0.029	Ω	
		$V_{GS}=4.5~V,~I_D=4~A$	-	0.026	0.033	1	
Forward Transconductance <sup>a</sup>	<b>g</b> fs	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 5 \text{ A}$	-	25	-	S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		-	490	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = 15 V, $V_{GS}$ = 0 V, f = 1 MHz	-	150	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-		
C <sub>rss</sub> /C <sub>iss</sub> Ratio			-	0.021	0.042	-	
Total Gate Charge	Qg	$V_{DS}$ = 15 V, $V_{GS}$ = 10 V, $I_{D}$ = 5 A	-	6.6	10	nC	
			-	3	4.5		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 15 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 5 A	-	1.4	-		
Gate-Drain Charge	Q <sub>gd</sub>		-	0.5	-		
Output Charge	Q <sub>oss</sub>	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	4.2	-		
Gate Resistance	Rg	f = 1 MHz	0.9	4.6	6.9	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		-	13	25	ns	
Rise Time	tr	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$	-	45	90		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 5$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$	-	13	25		
Fall Time	t <sub>f</sub>		-	25	50		
Turn-On Delay Time	t <sub>d(on)</sub>		-	5	10		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$	-	27	55		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V},  \text{R}_\text{g} = 1  \Omega$	-	10	20		
Fall Time	t <sub>f</sub>		-	8	15		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C -		-	4.5	A	
Pulse Diode Forward Current	I <sub>SM</sub>		-	-	30	~	
Body Diode Voltage	V <sub>SD</sub>	$I_S = 5 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.85	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	20	40	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s},$	-	7	15	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	T <sub>J</sub> = 25 °C	-	9.5	-		
· · · · · <b>,</b> · · · ·						ns	

#### Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

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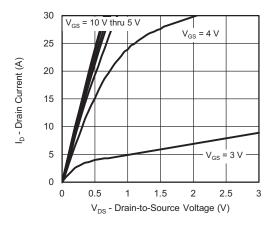
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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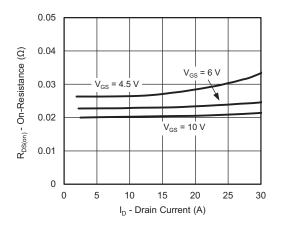
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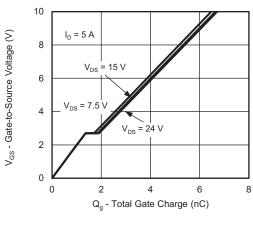
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



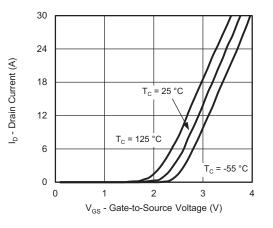
**Output Characteristics** 



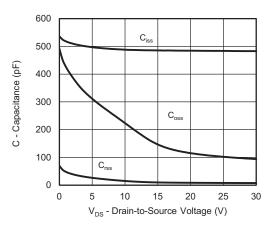
**On-Resistance vs. Drain Current and Gate Voltage** 



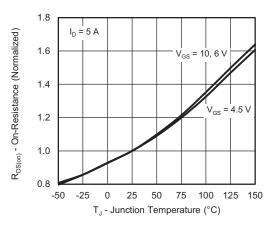
Gate Charge



**Transfer Characteristics** 



Capacitance



**On-Resistance vs. Junction Temperature** 

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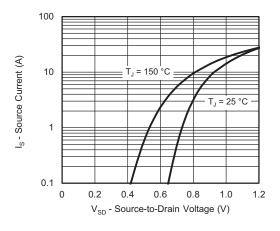
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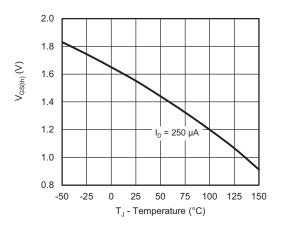
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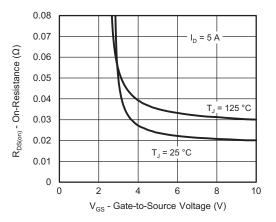
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



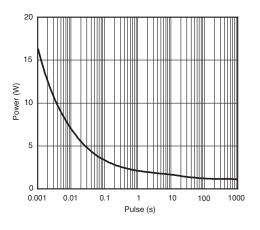
Source-Drain Diode Forward Voltage



**Threshold Voltage** 



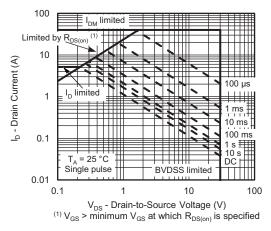
**On-Resistance vs. Gate-to-Source Voltage** 



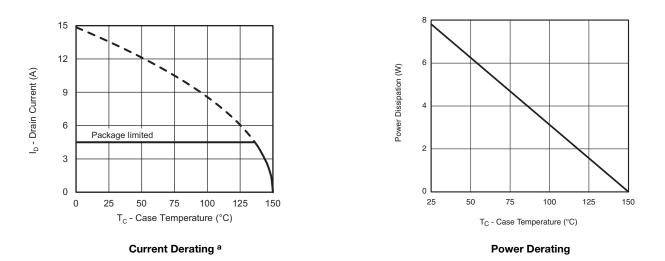
Single Pulse Power (Junction-to-Ambient)



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Safe Operating Area, Junction-to-Ambient

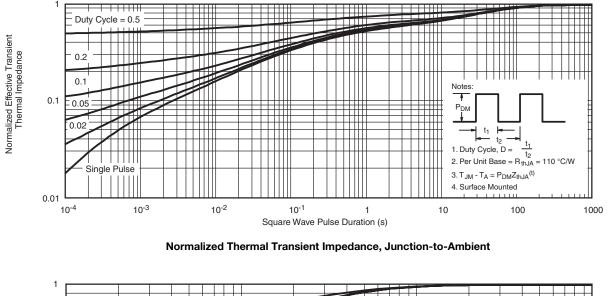


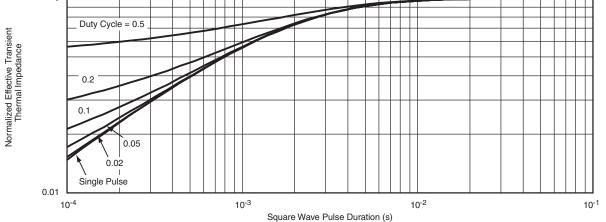
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Normalized Thermal Transient Impedance, Junction-to-Case

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